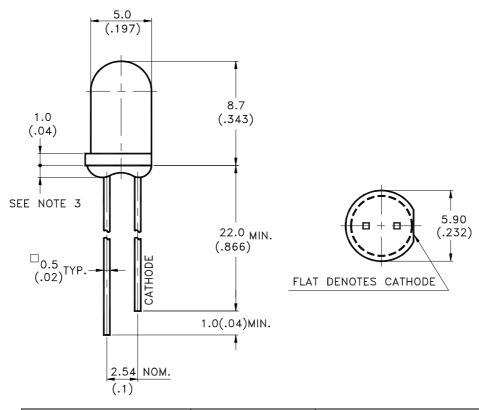


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#### **Features**

- \* Lead (Pb) free product RoHS compliant.
- \* High luminous intensity output.
- \* Low power consumption.
- \* High efficiency.
- \* Versatile mounting on P.C. board or panel.
- \* I.C. Compatible/low current requirements.
- \* Popular T-13/4 diameter.

#### **Package Dimensions**



Part No.	Lens	Source Color		
LTL2P3SYK-002	K-002 Water Clear AlInGaP Amb			

#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25$ mm(.010") unless otherwise noted.
- 3. Protruded resin under flange is 1.0mm(.04") max.
- 4. Lead spacing is measured where the leads emerge from the package.
- 5. Specifications are subject to change without notice.

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# LITEON LITE-ON TECHNOLOGY CORPORATION

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# Absolute Maximum Ratings at TA=25℃

Parameter	Maximum Rating	Unit
Power Dissipation	130	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	100	mA
Continuous Forward Current	50	mA
Derating Linear From 50°C	0.6	mA/°C
Reverse Voltage	5	V
Operating Temperature Range	-40°C to + 100°C	
Storage Temperature Range	-55°C to + 100°C	
Lead Soldering Temperature [2 mm(.0787") From Body]	260°C for 5 Seconds	

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# Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Luminous Intensity	Iv	1900	3700		mcd	I <sub>F</sub> = 20mA Note 1,5
Viewing Angle	2 θ 1/2		22		deg	Note 2 (Fig.5)
Peak Emission Wavelength	λР		591		nm	Measurement @Peak (Fig.1)
Dominant Wavelength	λd		590		nm	Note 4
Spectral Line Half-Width	Δλ		17		nm	
Forward Voltage	$V_{\mathrm{F}}$		2.35	2.7	V	$I_F = 20 \text{mA}$
Reverse Current	$I_R$			100	μΑ	$V_R = 5V$
Capacitance	С		40		pF	$V_F = 0$ , $f = 1MHz$

NOTE: 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.

- 2.  $\theta_{1/2}$  is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. Iv classification code is marked on each packing bag.
- 4. The dominant wavelength,  $\lambda$  d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 5. The Iv guarantee should be added  $\pm 15\%$  tolerance.

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### Typical Electrical / Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

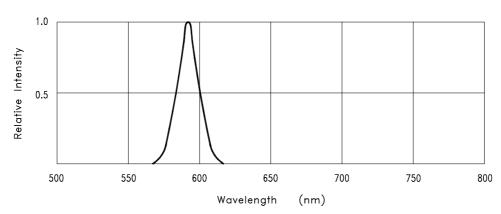
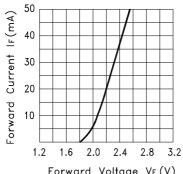


Fig.1 Relative Intensity vs. Wavelength



Forward Voltage VF(V)
Fig.2 Forward Current vs.
Forward Voltage

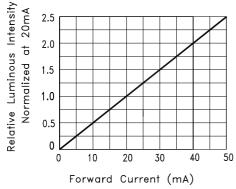
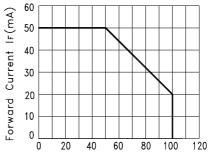


Fig.4 Relative Luminous Intensity vs. Forward Current



Ambient Temperature TA(°C)
Fig.3 Forward Current
Derating Curve

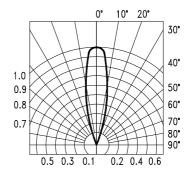


Fig.5 Spatial Distribution

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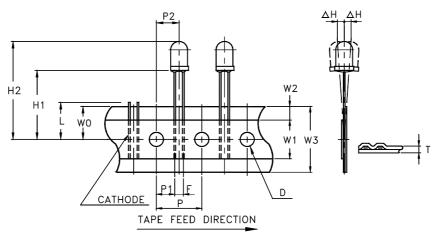
Property of Lite-On Only

#### **Features**

- \* Compatible with radial lead automatic insertion equipment.
- \* Most radial lead plastic lead lamps available packaged in tape and folding.
- \* 2.54mm (0.1") straight lead spacing available.
- \* Folding packaging simplifies handling and testing.

  Reel packaging is available by removing suffix "A" on option.

#### **Package Dimensions**



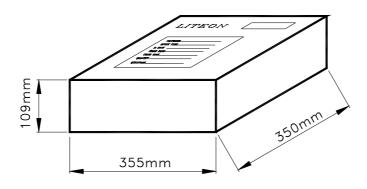
		Specification				
Item	Symbol	Mir	Minimum		imum	
		mm	inch	mm	inch	
Tape Feed Hole Diameter	D	3.8	0.149	4.2	0.165	
Component Lead Pitch	F	2.3	0.091	3.0	0.118	
Front to Rear Deflection	ΔΗ			2.0	0.078	
Feed Hole to Bottom of Component	H1	17.5	0.689	18.5	0.728	
Feed Hole to Overall Component Height	H2	25.9	25.9 1.020		1.083	
Lead Length After Component Height	L	V	W0		0.433	
Feed Hole Pitch	P	12.4	12.4 0.488		0.511	
Lead Location	P1	4.4	0.173	5.8	0.228	
Center of Component Location	P2	5.05	0.198	7.65	0.301	
Total Tape Thickness	T			0.90	0.035	
Feed Hole Location	W0	8.5	8.5 0.334		0.384	
Adhesive Tape Width	W1	14.5	0.571	15.5	0.610	
Adhesive Tape Position	W2	0	0	3.0	0.118	
Tape Width	W3	17.5	0.689	19.0	0.748	

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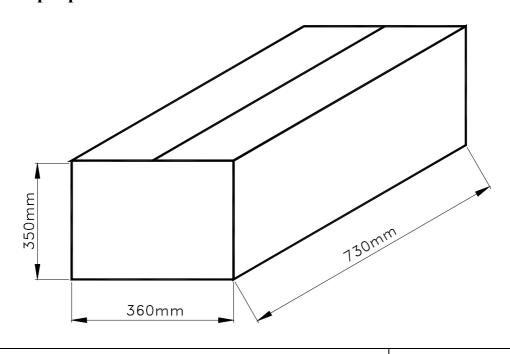
# Packing Spec

2 reel per inner carton total 2000pcs per inner carton



Tolerance: ±5mm

6 Inner cartons per outer carton total 12000 pcs per outer carton



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# **Bin Table Specification**

Luminous Intensity Iv(mcd) IF@20mA				
Bin Code	Min.	Max.		
S	1900	2500		
T	2500	3200		
U	3200	4200		
V	4200	5500		
W	5500	7200		
X	7200	9300		

Note: Tolerance of each bin limit is  $\pm 15\%$ 

Forward	Voltage Vf (Volts)	IF@20mA
Bin Code	Min.	Max.
1	1.8	1.9
2	1.9	2.0
3	2.0	2.1
4	2.1	2.2
5	2.2	2.3
6	2.3	2.4
7	2.4	2.5
8	2.5	2.6
9	2.6	2.7

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#### **CAUTIONS**

#### 1. Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

#### 2. Storage

The storage ambient for the LEDs should not exceed 30°C temperature or 70% relative humidity. It is recommended that LEDs out of their original packaging are used within three months. For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

#### 3. Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LEDs if necessary.

#### 4. Lead Forming & Assembly

During lead forming, the leads should be bent at a point at least 3mm from the base of LED lens.

Do not use the base of the lead frame as a fulcrum during forming.

Lead forming must be done before soldering, at normal temperature.

During assembly on PCB, use minimum clinch force possible to avoid excessive mechanical stress.

#### 5. Soldering

When soldering, leave a minimum of 2mm clearance from the base of the lens to the soldering point. Dipping the lens into the solder must be avoided.

Do not apply any external stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering conditions:

Soldering iron		Wave soldering		
Temperature Soldering time	300°C Max. 3 sec. Max. (one time only)	Pre-heat Pre-heat time Solder wave Soldering time	100°C Max. 60 sec. Max. 260°C Max. 5 sec. Max.	

Note: Excessive soldering temperature and/or time might result in deformation of the LED lens or catastrophic failure of the LED. IR reflow is not suitable process for through hole type LED lamp product.

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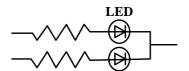
Property of Lite-On Only

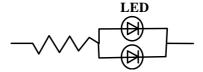
#### 6. Drive Method

An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.

Circuit model A

Circuit model B





- (A) Recommended circuit
- (B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs

#### 7. ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

Suggestions to prevent ESD damage:

- Use a conductive wrist band or anti- electrostatic glove when handling these LEDs
- All devices, equipment, and machinery must be properly grounded
- Work tables, storage racks, etc. should be properly grounded
- Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing

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#### Suggested checking list:

#### Training and Certification

- 1. Everyone working in a static-safe area is ESD-certified?
- 2. Training records kept and re-certification dates monitored?

#### Static-Safe Workstation & Work Areas

- 1. Static-safe workstation or work-areas have ESD signs?
- 2. All surfaces and objects at all static-safe workstation and within 1 ft measure less than 100V?
- 3. All ionizer activated, positioned towards the units?
- 4. Each work surface mats grounding is good?

#### Personnel Grounding

- 1. Every person (including visitors) handling ESD sensitive (ESDS) items wear wrist strap, heel strap or conductive shoes with conductive flooring?
- 2. If conductive footwear used, conductive flooring also present where operator stand or walk?
- 3. Garments, hairs or anything closer than 1 ft to ESD items measure less than 100V\*?
- 4. Every wrist strap or heel strap/conductive shoes checked daily and result recorded for all DLs?
- 5. All wrist strap or heel strap checkers calibration up to date? Note: \*50V for Blue LED.

## Device Handling

- 1. Every ESDS items identified by EIA-471 labels on item or packaging?
- 2. All ESDS items completely inside properly closed static-shielding containers when not at static-safe workstation?
- 3. No static charge generators (e.g. plastics) inside shielding containers with ESDS items?
- 4. All flexible conductive and dissipative package materials inspected before reuse or recycle?

#### Others

- 1. Audit result reported to entity ESD control coordinator?
- 2. Corrective action from previous audits completed?
- 3. Are audit records complete and on file?

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### 8. Reliability Test

Classification	Test Item	Test Condition	Reference Standard
	Operation Life	Ta= Under Room Temperature As Per Data Sheet Maximum Rating *Test Time= 1000HRS (-24HRS,+72HRS)	MIL-STD-750D:1026 (1995) MIL-STD-883D:1005 (1991) JIS C 7021:B-1 (1982)
	High Temperature High Humidity Storage	Ta= $65\pm5^{\circ}$ C RH= $90 \sim 95\%$ Test Time= $240$ HRS $\pm2$ HRS	MIL-STD-202F: 103B(1980) JIS C 7021 : B-11(1982)
Endurance Test	High Temperature High Humidity Reverse BIAS	Ta= $65\pm5^{\circ}$ C RH= $90 \sim 95\%$ VR=5V Test Time = $500$ HRS (- $24$ HRS, + $48$ HRS)	JIS C 7021 : B-11(1982)
	High Temperature Storage	Ta= 105±5°C *Test Time= 1000HRS (-24HRS,+72HRS)	MIL-STD-883D:1008 (1991) JIS C 7021:B-10 (1982)
	Low Temperature Storage	Ta= -55±5°C *Test Time=1000HRS (-24HRS,+72HRS)	JIS C 7021:B-12 (1982)
	Temperature Cycling	$105^{\circ}\text{C} \sim 25^{\circ}\text{C} \sim -55^{\circ}\text{C} \sim 25^{\circ}\text{C}$ 30mins 5mins 30mins 5mins 10  Cycles	MIL-STD-202F:107D (1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1010 (1991) JIS C 7021: A-4(1982)
Environmental	Thermal Shock	$105 \pm 5^{\circ}\text{C} \sim -55^{\circ}\text{C} \pm 5^{\circ}\text{C}$ 10mins $10mins10 Cycles$	MIL-STD-202F:107D(1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1011 (1991)
Test	Solder Resistance	T.sol = 260 °C Max Dwell Time= 5 secs Max	MIL-STD-202F:210A(1980) MIL-STD-750D:2031(1995) JIS C 7021: A-1(1982)
	Solderability	T. sol = $230 \pm 5^{\circ}$ C Dwell Time= $5 \pm 1$ secs	MIL-STD-202F:208D(1980) MIL-STD-750D:2026(1995) MIL-STD-883D:2003(1991) JIS C 7021: A-2(1982)

#### 9. Others

The appearance and specifications of the product may be modified for improvement, without prior notice.

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